



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

#10/FID
7/16/2
Hupler

In re Application of:

Moon et al.

Serial No.: 09/874,631

Filed: June 5, 2001

For: FLEXIBLE BALL GRID ARRAY CHIP
SCALE PACKAGES AND METHODS OF
FABRICATION

Examiner: S. Clark

Group Art Unit: 2815

Attorney Docket No.: 4368US (99-0959)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

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1.8(a)(i)(ii)

Joseph A. Walkowski
Typed/printed name of person whose signature is
contained above

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

Sir:

Attached please find corrected formal drawings for this application.

Respectfully submitted,

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Date: June 28, 2002

JAW/dlm

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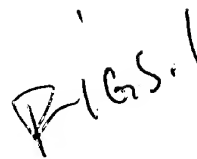


Fig. 1(a)

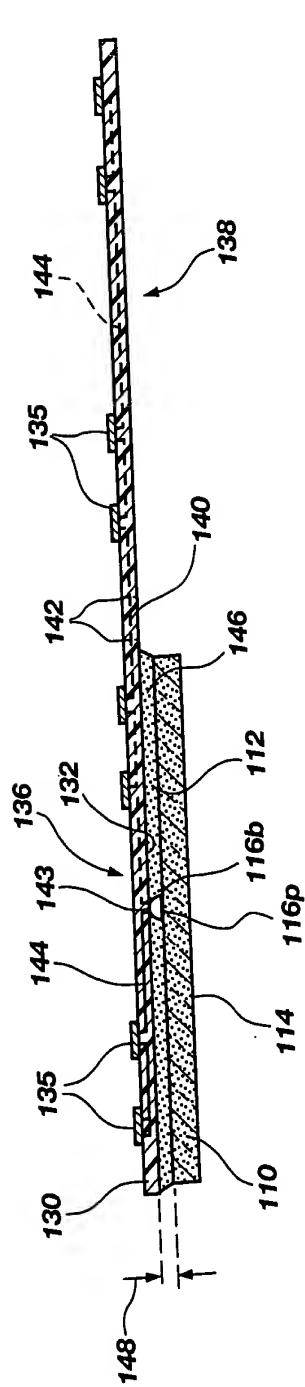


Fig. 1(b)

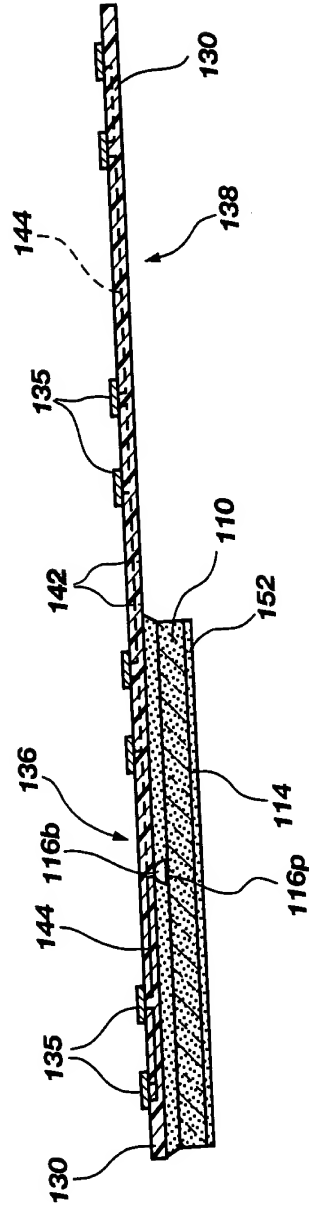
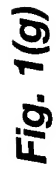
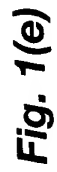


Fig. 1(c)



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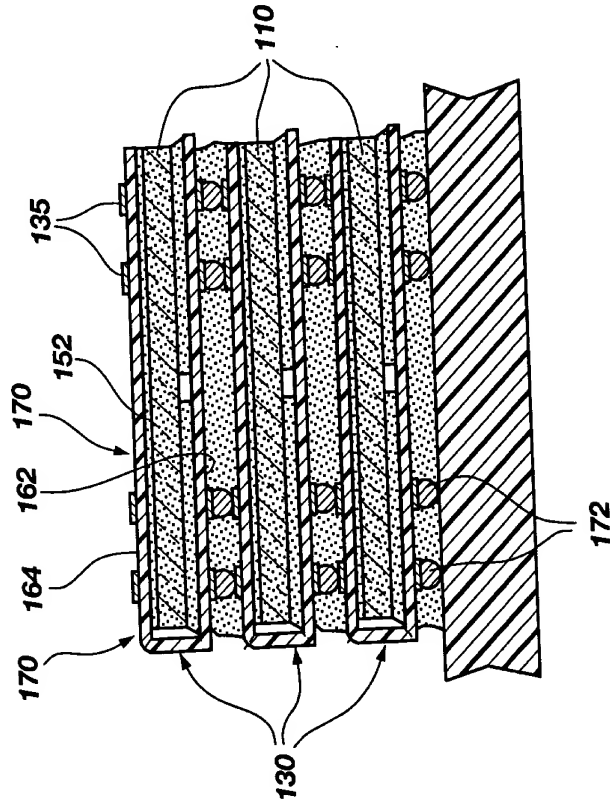


Fig. 2(b)

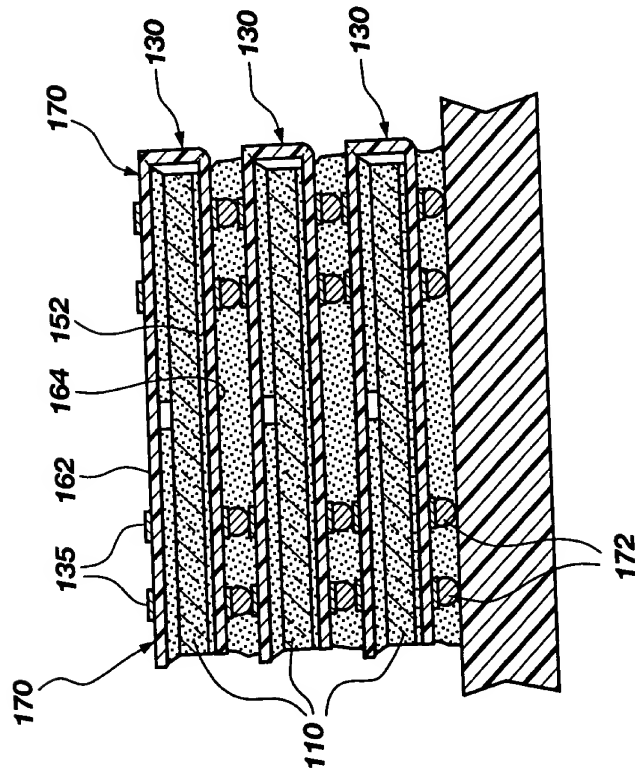


Fig. 2(a)

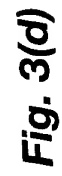


Fig. 3(c)

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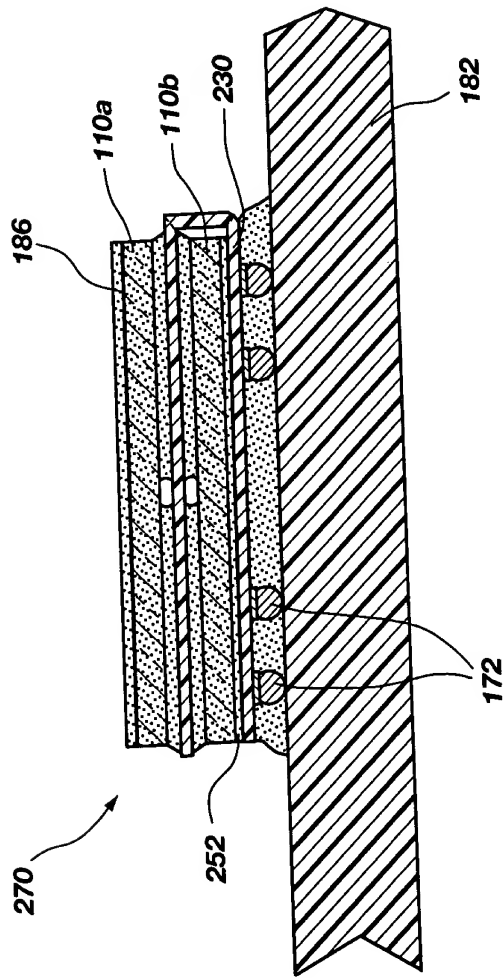


Fig. 3(e)

